

Features

- High voltage capability
- High speed

Applications

- Home appliance
- Lighting

Description

This device is a very fast IGBT developed using advanced PowerMESH™ technology. This process guarantees an excellent trade-off between switching performance and low on-state behavior. This device is well-suited for resonant or soft-switching applications.

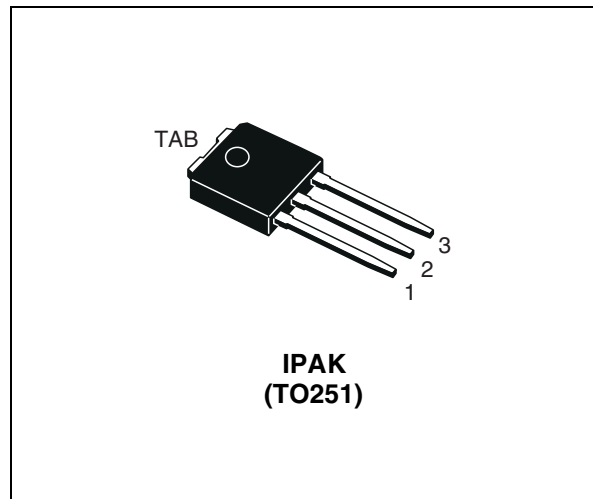


Figure 1. Internal schematic diagram

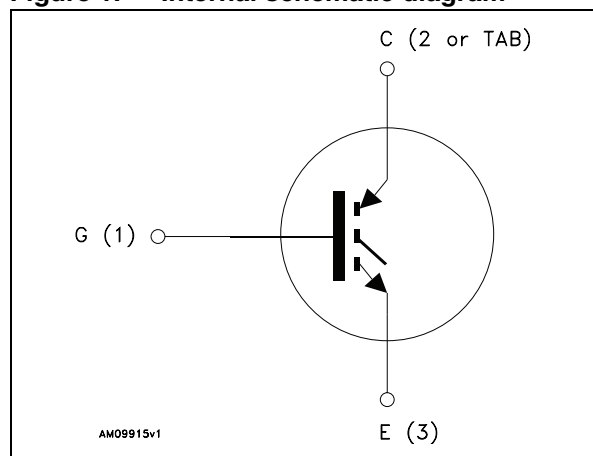


Table 1. Device summary

Order code	Marking	Package	Packaging
STGD3NC120H-1	GD3NC120H	IPAK (TO251)	Tube

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1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CES}	Collector-emitter voltage ($V_{GE} = 0$)	1200	V
$I_C^{(1)}$	Continuous collector current at $T_C = 25\text{ °C}$	16	A
$I_C^{(1)}$	Continuous collector current at $T_C = 100\text{ °C}$	9	A
$I_{CL}^{(2)}$	Turn-off latching current	14	A
$I_{CP}^{(3)}$	Pulsed collector current	20	A
V_{GE}	Gate-emitter voltage	± 20	V
P_{TOT}	Total dissipation at $T_C = 25\text{ °C}$	105	W
T_J	Operating junction temperature	-55 to 150	$^{\circ}\text{C}$

1. Calculated according to the iterative formula:

$$I_C(T_C) = \frac{T_{j(\max)} - T_C}{R_{thj-c} \times V_{CE(\text{sat})(\max)}(T_{j(\max)}, I_C(T_C))}$$

2. $V_{\text{clamp}} = 80\% V_{CES}$, $T_j = 150\text{ °C}$, $R_G = 10\ \Omega$, $V_{GE} = 15\text{ V}$
 3. Pulse width limited by maximum junction temperature and turn-off within RBSOA

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance junction-case IGBT	1.2	$^{\circ}\text{C}/\text{W}$
R_{thJA}	Thermal resistance junction-ambient	100	$^{\circ}\text{C}/\text{W}$

2 Electrical characteristics

$T_J = 25\text{ °C}$ unless otherwise specified.

Table 4. Static electrical characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage ($V_{GE} = 0$)	$I_C = 1\text{ mA}$	1200			V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}, I_C = 3\text{ A}$ $V_{GE} = 15\text{ V}, I_C = 3\text{ A}, T_J = 125\text{ °C}$		2.3 2.2	2.8	V V
$V_{GE(th)}$	Gate threshold voltage	$V_{CE} = V_{GE}, I_C = 250\text{ }\mu\text{A}$	2		5	V
I_{CES}	Collector cut-off current ($V_{GE} = 0$)	$V_{CE} = 1200\text{ V}$ $V_{CE} = 1200\text{ V}, T_J = 125\text{ °C}$			50 1	μA mA
I_{GES}	Gate-emitter leakage current ($V_{CE} = 0$)	$V_{GE} = \pm 20\text{ V}$			± 100	nA
$g_{fs}^{(1)}$	Forward transconductance	$V_{CE} = 25\text{ V}, I_C = 3\text{ A}$		4		S

1. Pulse duration: 300 μs , duty cycle 1.5%

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies}	Input capacitance	$V_{CE} = 25\text{ V}, f = 1\text{ MHz}, V_{GE} = 0$	-	470	-	pF
C_{oes}	Output capacitance			45		pF
C_{res}	Reverse transfer capacitance			6		pF
Q_g	Total gate charge	$V_{CE} = 960\text{ V},$ $I_C = 3\text{ A}, V_{GE} = 15\text{ V}$	-	24	-	nC
Q_{ge}	Gate-emitter charge			3		nC
Q_{gc}	Gate-collector charge			10		nC

Table 6. Switching on/off (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CC} = 800\text{ V}, I_C = 3\text{ A}$	-	15	-	ns
t_r	Current rise time	$R_G = 10\ \Omega, V_{GE} = 15\text{ V},$ (see Figure 18)	-	3.5	-	ns
$(di/dt)_{on}$	Turn-on current slope			880		A/ μ s
$t_{d(on)}$	Turn-on delay time	$V_{CC} = 800\text{ V}, I_C = 3\text{ A}$	-	14.5	-	ns
t_r	Current rise time	$R_G = 10\ \Omega, V_{GE} = 15\text{ V},$ $T_J = 125\text{ }^\circ\text{C}$ (see Figure 18)	-	4	-	ns
$(di/dt)_{on}$	Turn-on current slope			770		A/ μ s
$t_r(V_{off})$	Off voltage rise time	$V_{CC} = 800\text{ V}, I_C = 3\text{ A}$	-	72	-	ns
$t_{d(off)}$	Turn-off delay time	$R_G = 10\ \Omega, V_{GE} = 15\text{ V},$ (see Figure 18)	-	118	-	ns
t_f	Current fall time			250		ns
$t_r(V_{off})$	Off voltage rise time	$V_{CC} = 800\text{ V}, I_C = 3\text{ A}$	-	132	-	ns
$t_{d(off)}$	Turn-off delay time	$R_G = 10\ \Omega, V_{GE} = 15\text{ V},$ $T_J = 125\text{ }^\circ\text{C}$ (see Figure 18)	-	210	-	ns
t_f	Current fall time			470		ns

Table 7. Switching energy (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$E_{on}^{(1)}$	Turn-on switching losses	$V_{CC} = 800\text{ V}, I_C = 3\text{ A}$	-	236	-	μ J
$E_{off}^{(2)}$	Turn-off switching losses	$R_G = 10\ \Omega, V_{GE} = 15\text{ V},$ (see Figure 18)	-	290	-	μ J
E_{ts}	Total switching losses			526		μ J
$E_{on}^{(1)}$	Turn-on switching losses	$V_{CC} = 800\text{ V}, I_C = 3\text{ A}$	-	360	-	μ J
$E_{off}^{(2)}$	Turn-off switching losses	$R_G = 10\ \Omega, V_{GE} = 15\text{ V},$ $T_J = 125\text{ }^\circ\text{C}$ (see Figure 18)	-	620	-	μ J
E_{ts}	Total switching losses			980		μ J

1. E_{on} is the turn-on losses when a typical diode is used in the test circuit in figure 2. If the IGBT is offered in a package with a co-pack diode, the co-pack diode is used as external diode. IGBTs & Diode are at the same temperature (25 °C and 125 °C)
2. Turn-off losses include also the tail of the collector current

2.1 Electrical characteristics (curves)

Figure 2. Output characteristics

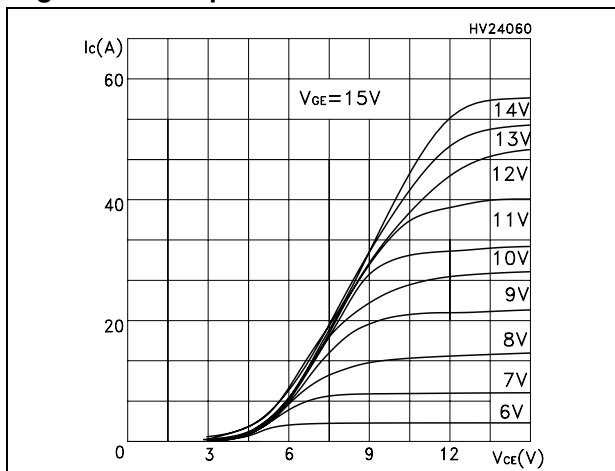


Figure 3. Transfer characteristics

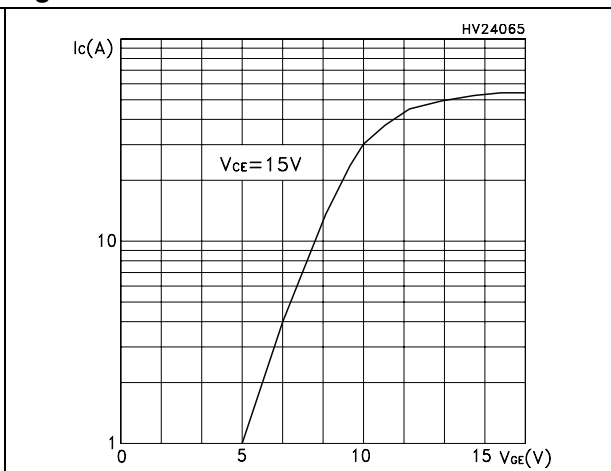


Figure 4. Transconductance

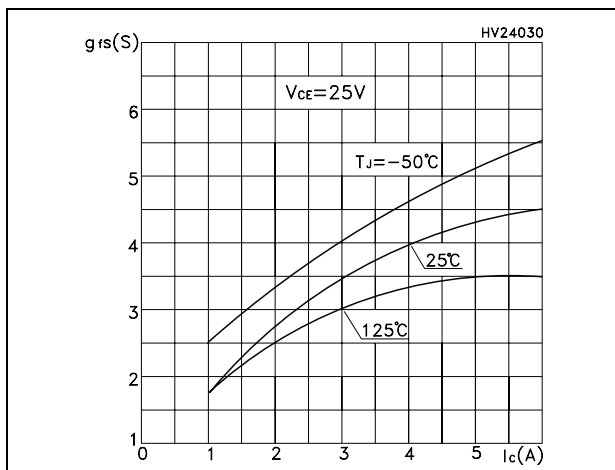


Figure 5. Collector-emitter on voltage vs. temperature

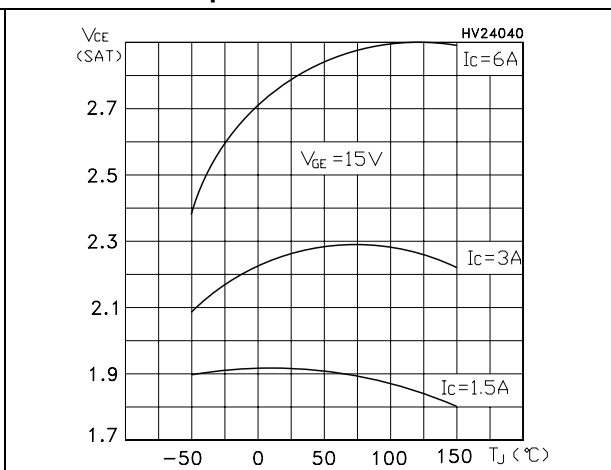


Figure 6. Collector-emitter on voltage vs. collector current

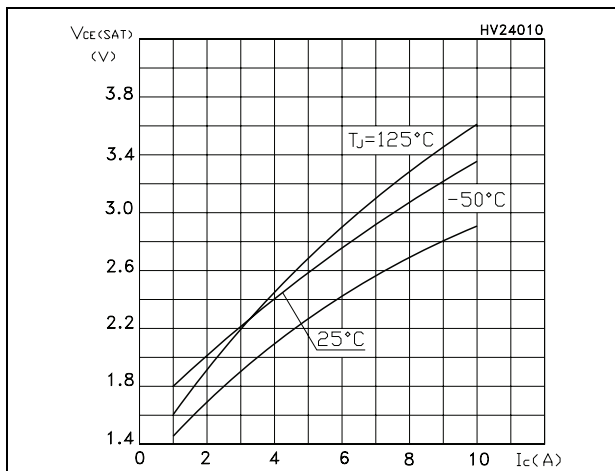


Figure 7. Normalized gate threshold voltage vs. temperature

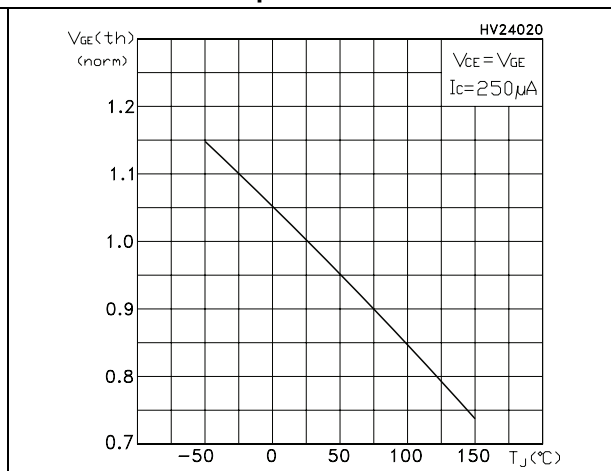


Figure 8. Normalized breakdown voltage vs. temperature

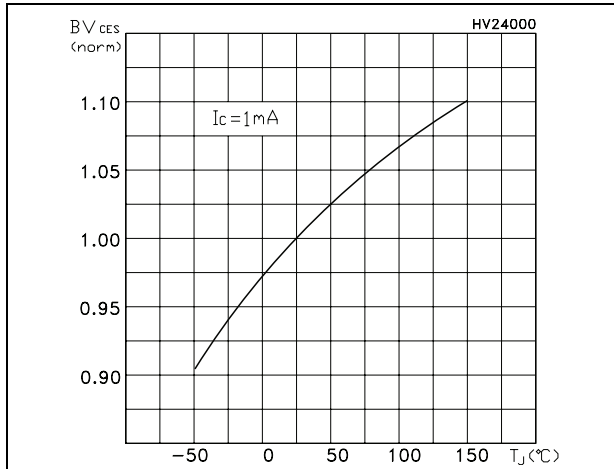


Figure 9. Gate charge vs. gate-source voltage

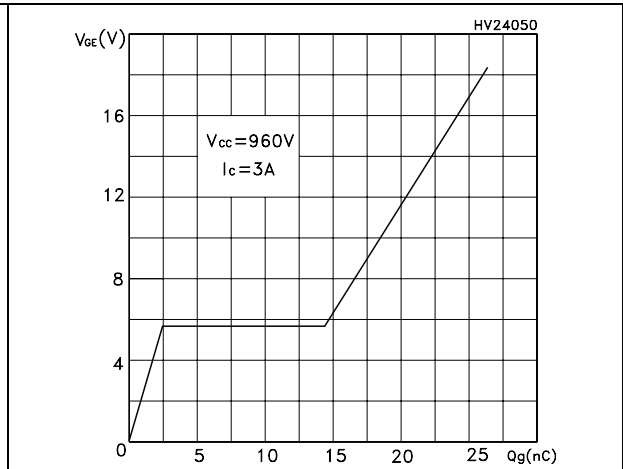


Figure 10. Capacitance variations

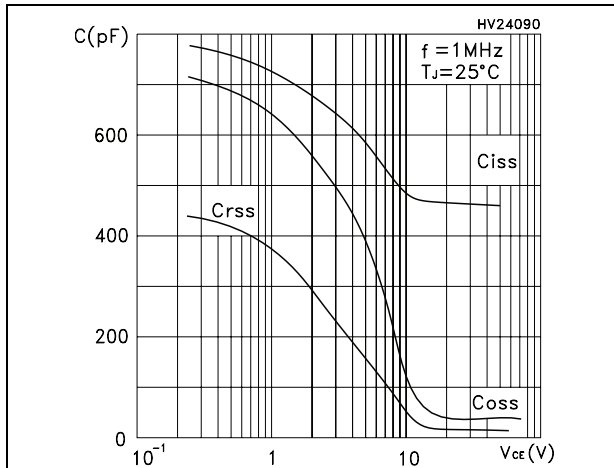


Figure 11. Switching losses vs. temperature

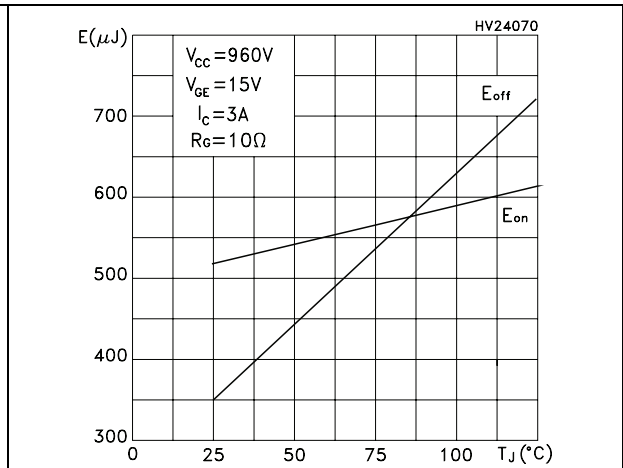


Figure 12. Switching losses vs. gate resistance

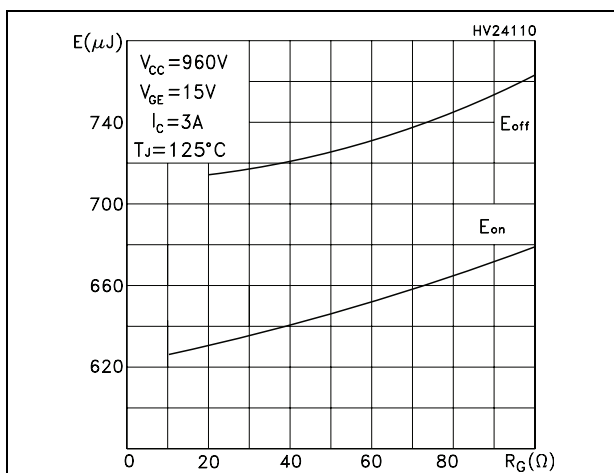


Figure 13. Switching losses vs. collector current

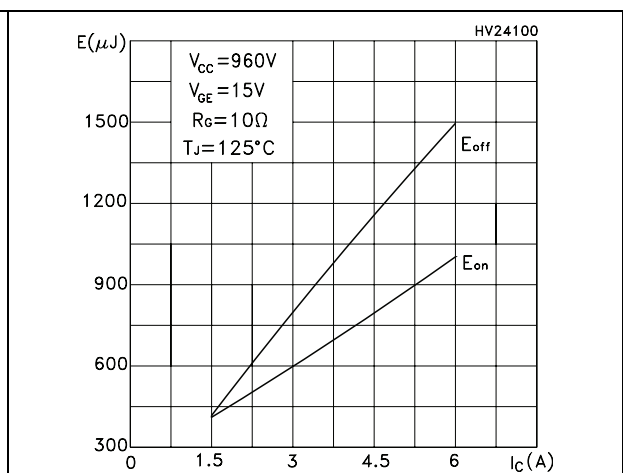


Figure 14. Power losses @ $I_C = 3\text{ A}$

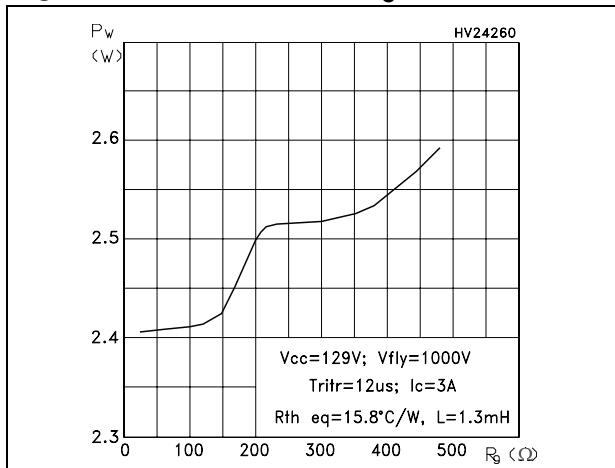


Figure 15. Power losses @ $I_C = 2\text{ A}$

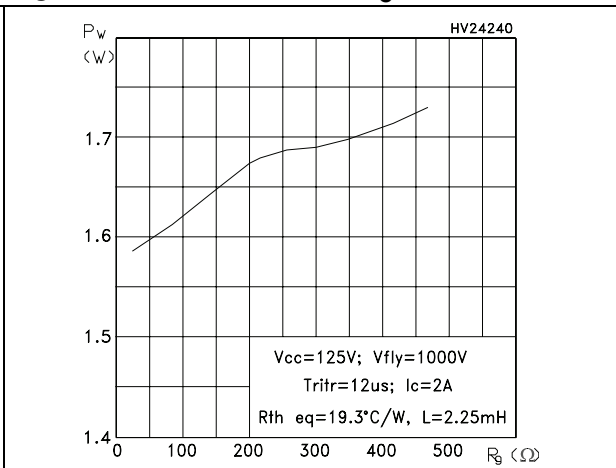


Figure 16. Turn-off SOA

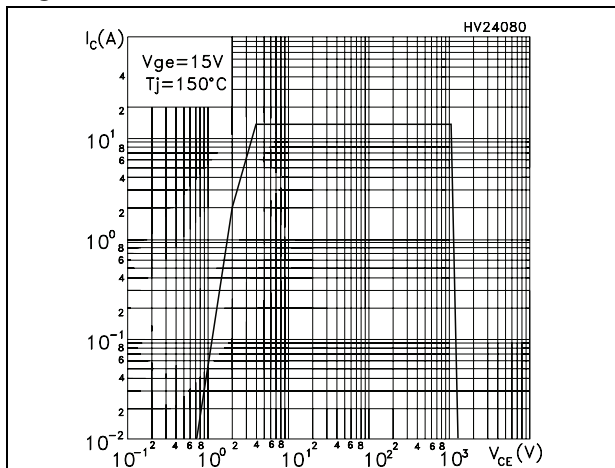
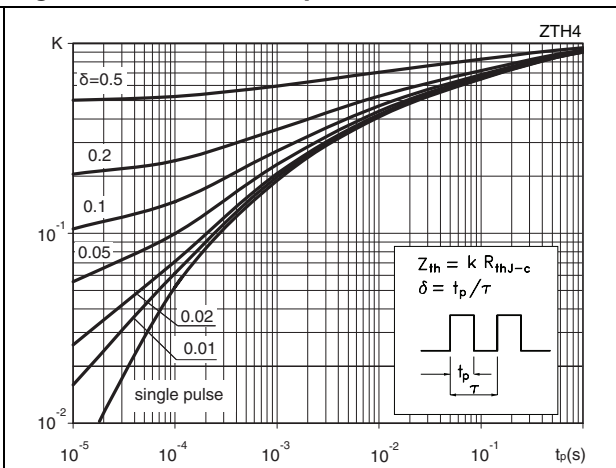


Figure 17. Thermal impedance



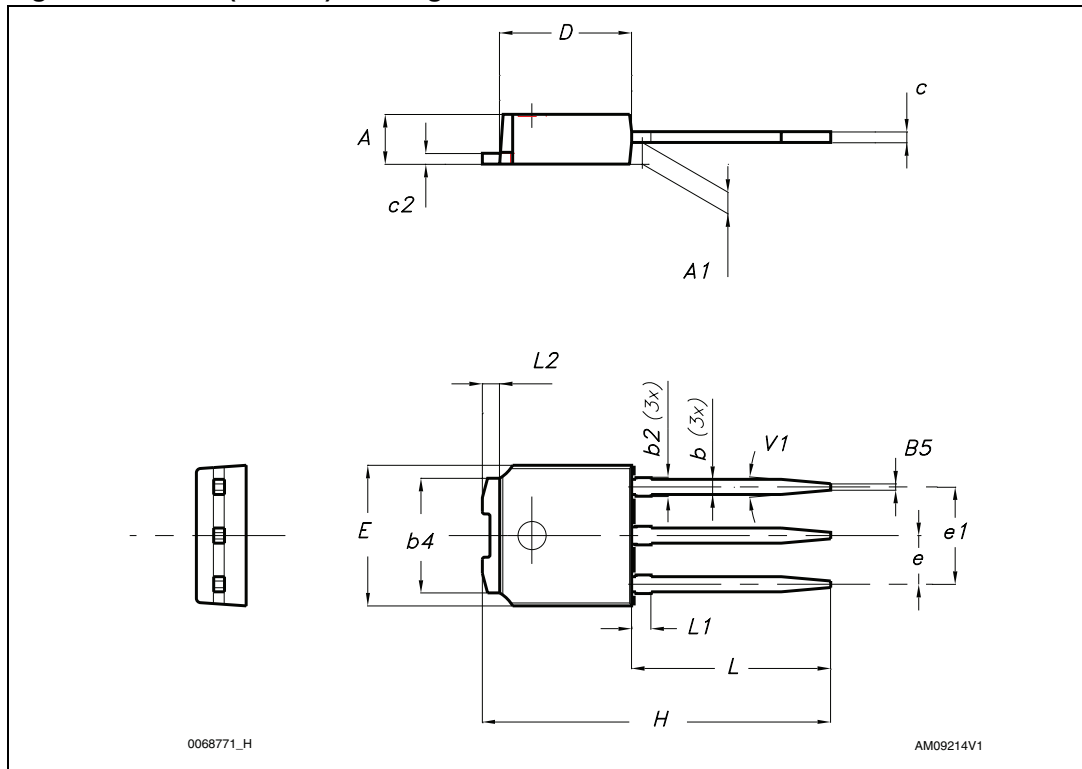
4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Table 8. IPAK (TO-251) mechanical data

DIM.	mm.		
	min.	typ	max.
A	2.20		2.40
A1	0.90		1.10
b	0.64		0.90
b2			0.95
b4	5.20		5.40
B5		0.3	
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
E	6.40		6.60
e		2.28	
e1	4.40		4.60
H		16.10	
L	9.00		9.40
L1	0.80		1.20
L2		0.80	1.00
V1		10 °	

Figure 21. IPAK (TO-251) drawing



5 Revision history

Table 9. Document revision history

Date	Revision	Changes
27-Jun-2012	1	First release.

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